

# **Film Capacitors**

## Metallized Polyester Film Capacitors (MKT)

Series/Type: B32232 Date: May 2009

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Metallized polyester film capacitors (MKT)

## General purpose (wound)

## Typical applications

- Smoothing
- Filtering

#### Climatic

- Max. operating temperature: 100 °C
- Climatic category (IEC 60068-1): 40/100/21

## Construction

- Dielectric: polyethylene terephthalate (polyester, PET)
- Cylindrical winding
- Insulating sleeve
- Face ends sealed with epoxy resin

### Terminals

Central axial wire leads, lead-free tinned

## Marking

Manufacturer, series number, rated capacitance (coded), capacitance tolerance (code letter), rated DC voltage. date of manufacture (coded)

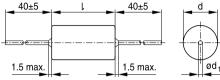
#### **Delivery mode**

Bulk (untaped) Taped (reel) For notes on taping, refer to chapter "Taping and packing".

#### **Detail specification**

DIN 45910-112

## **Dimensional drawing**





Dimensions in mm

Diameter d	Lead diameter d <sub>1</sub>	
≤ 7.0	0.6	
> 7.0	0.8	

When bending leads take care to leave a clearance of 1 mm to the capacitor body.



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## Overview of available types

Туре	B32232			
V <sub>R</sub> (V DC)	100	250	400	630
V <sub>RMS</sub> (V AC)	63	160	200	200
C <sub>R</sub> (μF)				
0.033				
0.047				
0.068				
0.10				
0.15				
0.22				
0.33				
0.47				
0.68				
1.0				
1.5				
2.2				
3.3				
4.7				
6.8				





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## Ordering codes and packing units

V <sub>R</sub>	$V_{\text{RMS}}$	C <sub>R</sub>	Max. dimensions	Ordering code	Reel	Untaped
	f ≤60 Hz		d×I	(composition see		
V DC	V AC	μF	mm	below)	pcs./MOQ	pcs./MOQ
100	63	0.10	6.0×14.0	B32232A1104+***	4000	2000
		0.15	6.0  imes 14.0	B32232A1154+***	4000	2000
		0.22	6.0  imes 14.0	B32232A1224+***	4000	2000
		0.33	6.0  imes 19.0	B32232A1334+***	4000	2000
		0.47	6.5  imes 19.0	B32232A1474+***	4000	2000
		0.68	7.0  imes 19.0	B32232A1684+***	4000	2000
		1.0	8.5 × 19.0	B32232A1105+***	4000	2000
		1.5	8.0×27.0	B32232A1155+***	4000	2000
		2.2	9.5×27.0	B32232A1225+***	3600	2000
		3.3	$11.5 \times 27.0$	B32232A1335+***	2000	2000
		4.7	12.0 × 32.0	B32232A1475+***	2000	2000
		6.8	14.0 × 32.0	B32232A1685+***	2000	1000
250	160	0.10	6.0×14.0	B32232A3104+***	4000	2000
		0.15	7.0  imes 14.0	B32232A3154+***	4000	2000
		0.22	6.0  imes 19.0	B32232A3224+***	4000	2000
		0.33	7.0  imes 19.0	B32232A3334+***	4000	2000
		0.47	8.0 × 19.0	B32232A3474+***	4000	2000
		0.68	8.0×27.0	B32232A3684+***	4000	2000
		1.0	$10.0 \times 27.0$	B32232A3105+***	2000	2000
		1.5	10.0 × 32.0	B32232A3155+***	2000	2000
		2.2	11.0 × 32.0	B32232A3225+***	2000	2000
		3.3	14.0 × 32.0	B32232A3335+***	2000	1000
		4.7	16.5  imes 32.0	B32232A3475+000	-	1000
		6.8	16.0 × 42.0	B32232A3685+000	_	800
400	200	0.10	7.0  imes 19.0	B32232A6104+***	4000	2000
		0.15	8.5  imes 19.0	B32232A6154+***	4000	2000
		0.22	8.0×27.0	B32232A6224+***	4000	2000
		0.33	9.5  imes 27.0	B32232A6334+***	3200	2000
		0.47	$11.0 \times 27.0$	B32232A6474+***	2000	2000
		0.68	11.5  imes 32.0	B32232A6684+***	2000	2000
		1.0	$13.5\times32.0$	B32232A6105+***	2000	2000

MOQ = Minimum Order Quantity, consisting of 4 packing units. Further E series and intermediate capacitance values on request.

### Composition of ordering code

+ = Capacitance tolerance code:

K = ±10%

 $J = \pm 5\%$ 

\*\*\* = Packaging code: 189 = Reel 000 = Untaped



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## Ordering codes and packing units

V <sub>R</sub>	V <sub>RMS</sub>	C <sub>R</sub>	Max. dimensions	Ordering code	Reel	Untaped
	f ≤60 Hz		$d \times I$	(composition see		
V DC	V AC	μF	mm	below)	pcs./MOQ	pcs./MOQ
630	200	0.033	6.5  imes 19.0	B32232A8333+***	4000	2000
		0.047	7.5  imes 19.0	B32232A8473+***	4000	2000
		0.068	8.5  imes 19.0	B32232A8683+***	4000	2000
		0.10	10.5  imes 19.0	B32232A8104+***	2000	2000
		0.15	$10.0 \times 27.0$	B32232A8154+***	2000	2000
		0.22	$11.5 \times 27.0$	B32232A8224+***	2000	2000
		0.33	$13.5 \times 27.0$	B32232A8334+***	2000	2000
		0.47	14.5  imes 32.0	B32232A8474+000	-	2000
		0.68	15.0  imes 32.0	B32232A8684+000	—	2000
		1.0	$16.0\times32.0$	B32232A8105+000	-	2000

MOQ = Minimum Order Quantity, consisting of 4 packing units. Further E series and intermediate capacitance values on request.

#### Composition of ordering code

+ = Capacitance tolerance code:
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 $K = \pm 10\%$ 

 $J = \pm 5\%$ 

\*\*\* = Packaging code: 189 = Reel 000 = Untaped





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## Technical data

Operating temperature range	Max. operati	ng temperature	e T <sub>op,max</sub>	+100 °C	
	Upper categ	ory temperatur	e T <sub>max</sub>	+100 °C	
	Lower categ	ory temperatur	e T <sub>min</sub>	−40 °C	
	Rated tempe	erature T <sub>R</sub>		+85 °C	
Dissipation factor tan $\delta$ (in 10 <sup>-3</sup> )	at	C <sub>R</sub> ≤ 47 nF	47 nF < C <sub>F</sub>	i≤1μF	C <sub>R</sub> > 1 μF
at 20 °C	1 kHz	10	10		10
(upper limit values)	10 kHz	20	25		-
Insulation resistance R <sub>ins</sub>	V <sub>R</sub>	$C_R \le 0.33  \mu F$		$C_{R} > 0.33$	μF
or time constant $\tau$ = C_R $\cdot$ $R_{\text{ins}}$	100 V DC	3750 MΩ		1250 s	
at 20 °C, rel. humidity $\leq$ 65%	$\geq$ 250 V DC	7500 MΩ		2500 s	
(minimum as-delivered values)	s)				
DC test voltage	1.4 · V <sub>R</sub> , 2 s				
Category voltage $V_c$	T <sub>A</sub> (°C)	DC voltage de	erating	AC voltage derating	
(continuous operation with $V_{\mbox{\tiny DC}}$	$T_A \le 85$	$V_{C} = V_{R}$		$V_{C,RMS} = V_{RMS}$	
or $V_{AC}$ at f $\leq$ 60 Hz)	$85 < T_A \le 100$	$V_{\rm C} = V_{\rm R} \cdot (165)$	5-T <sub>A</sub> )/80	$V_{C,RMS} = V_{RMS} \cdot (165 - T_A)/80$	
Operating voltage $V_{op}$ for	T <sub>A</sub> (°C)	DC voltage (m	nax. hours)	AC voltage (max. hours)	
short operating periods	$T_A \le 100$	$V_{op} = 1.25 \cdot V$	<sub>c</sub> (2000 h)	$V_{op} = 1.0 \cdot V_{C,RMS} (1000 \text{ h})$	
( $V_{DC}$ or $V_{AC}$ at f $\leq$ 60 Hz)					
Damp heat test	21 days/40 °	C/93% relative	humidity		
Limit values after damp	Capacitance change $ \Delta C/C  \leq 5\%$				
heat test	Dissipation factor change $\Delta \tan \delta \leq 5 \cdot 10^{-3}$		(at 1 kHz)		
				$\leq 7 \cdot 10^{-3}$	(at 10 kHz)
	Insulation re	sistance R <sub>ins</sub>		$\geq 20\%$ of	minimum
	or time cons	$\tan \tau = C_R \cdot R_i$	ns	as-deliver	red values



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## Pulse handling capability

"dV/dt" represents the maximum permissible voltage change per unit of time for non-sinusoidal voltages, expressed in  $V/\mu s$ .

"k\_0" represents the maximum permissible pulse characteristic of the waveform applied to the capacitor, expressed in V<sup>2</sup>/µs.

Note:

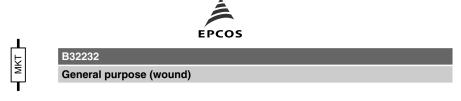
The values of dV/dt and  $k_0$  provided below must not be exceeded in order to avoid damaging the capacitor.

## dV/dt values

Length of capacitor 14 mm		19 mm	27 mm	32 mm	42 mm	
V <sub>R</sub>	V <sub>RMS</sub>					
V DC	V AC	dV/dt in V/µs				
100	63	6	3	2	1.5	-
250	160	10	5	3	2.5	2
400	200	-	7	4	3	-
630	200	_	10	7	5	-

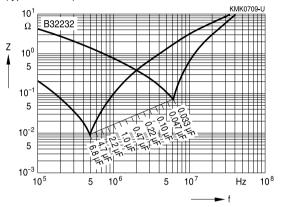
k<sub>0</sub> values

Length of c	apacitor	14 mm	19 mm	27 mm	32 mm	42 mm
V <sub>R</sub>	V <sub>RMS</sub>		•			
V DC	V AC	$k_0$ in V²/ $\mu$ s				
100	63	1 200	600	400	300	—
250	160	5 000	2 500	1 500	1 250	1 000
400	200	-	5 600	3 200	2 400	-
630	200	_	12 500	8 800	6 300	-



## Impedance Z versus frequency f

(typical values)



## Permissible AC voltage $V_{\mbox{\tiny RMS}}$ versus frequency f

Values can be obtained on request. In specific cases please provide a scaled voltage/ time graph and state operating conditions.





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## Mounting guidelines

## 1 Soldering

## 1.1 Solderability of leads

The solderability of terminal leads is tested to IEC 60068-2-20, test Ta, method 1.

Before a solderability test is carried out, terminals are subjected to accelerated ageing (to IEC 60068-2-2, test Ba: 4 h exposure to dry heat at 155 °C). Since the ageing temperature is far higher than the upper category temperature of the capacitors, the terminal wires should be cut off from the capacitor before the ageing procedure to prevent the solderability being impaired by the products of any capacitor decomposition that might occur.

Solder bath temperature	235 ±5 °C
Soldering time	2.0 ±0.5 s
Immersion depth	2.0 +0/ $-0.5$ mm from capacitor body or seating plane
Evaluation criteria:	
Visual inspection	Wetting of wire surface by new solder $\ge$ 90%, free-flowing solder

## 1.2 Resistance to soldering heat

Resistance to soldering heat is tested to IEC 60068-2-20, test Tb, method 1A. Conditions:

Serie	S	Solder bath temperature	Soldering time
MKT	boxed (except $2.5 \times 6.5 \times 7.2$ mm) coated uncoated (lead spacing > 10 mm)	260 ±5 °C	10 ±1 s
MFP MKP	(lead spacing > 7.5 mm)		
MKT	boxed (case $2.5 \times 6.5 \times 7.2$ mm)		5±1 s
МКР МКТ	(lead spacing $\leq$ 7.5 mm) uncoated (lead spacing $\leq$ 10 mm) insulated (B32559)		< 4 s recommended soldering profile for MKT uncoated (lead spacing $\leq$ 10 mm) and insulated (B32559)

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		КМК1242-V	
300			
°C	260 °C, 4	4 s	
250	<u>_</u>		
200			
150	-+ + +		
100			
50			
0 50			
0 00	-	—→ t	
Immersion dep	oth	2.0 +0/ $-0.5$ mm from capacitor body or seating plane	
Shield		Heat-absorbing board, (1.5 $\pm$ 0.5) mm thick, between capacitor	
		body and liquid solder	
Evaluation crit	eria:		
Visual inspection		No visible damage	
$\Delta C/C_0$		2% for MKT/MKP/MFP	
Ū		5% for EMI suppression capacitors	
tan δ		As specified in sectional specification	



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1.3 General notes on soldering

Permissible heat exposure loads on film capacitors are primarily characterized by the upper category temperature  $T_{max}$ . Long exposure to temperatures above this type-related temperature limit can lead to changes in the plastic dielectric and thus change irreversibly a capacitor's electrical characteristics. For short exposures (as in practical soldering processes) the heat load (and thus the possible effects on a capacitor) will also depend on other factors like:

- Pre-heating temperature and time
- Forced cooling immediately after soldering
- Terminal characteristics:
- diameter, length, thermal resistance, special configurations (e.g. crimping)
- Height of capacitor above solder bath
- Shadowing by neighboring components
- Additional heating due to heat dissipation by neighboring components
- Use of solder-resist coatings

The overheating associated with some of these factors can usually be reduced by suitable countermeasures. For example, if a pre-heating step cannot be avoided, an additional or reinforced cooling process may possibly have to be included.

EPCOS recommends the following conditions:

- Pre-heating with a maximum temperature of 110 °C
- Temperature inside the capacitor should not exceed the following limits:
  - MKP/MFP 110 °C
  - MKT 160 °C
- When SMD components are used together with leaded ones, the leaded film capacitors should not pass into the SMD adhesive curing oven. The leaded components should be assembled after the SMD curing step.
- Leaded film capacitors are not suitable for reflow soldering.

## **Uncoated capacitors**

For uncoated MKT capacitors with lead spacings  $\leq$ 10 mm (B32560/B32561) the following measures are recommended:

- pre-heating to not more than 110 °C in the preheater phase
- rapid cooling after soldering





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## 2 Cleaning

To determine whether the following solvents, often used to remove flux residues and other substances, are suitable for the capacitors described, refer to the table below:

Туре	Ethanol, isopropanol, n-propanol	n-propanol-water mixtures, water with surface tension-reducing tensides (neutral)	Solvent from table A (see next page)	Solvent from table B (see next page)
MKT (uncoated)	Suitable	Unsuitable	In part suitable	Unsuitable
MKT, MKP, MFP (coated/boxed)		Suitable	Suitable	

Even when suitable solvents are used, a reversible change of the electrical characteristics may occur in uncoated capacitors immediately after they are washed. Thus it is always recommended to dry the components (e.g. 4 h at 70  $^{\circ}$ C) before they are subjected to subsequent electrical testing.

## Table A

Manufacturers' designations for trifluoro-trichloro-ethane-based cleaning solvents (selection)

Trifluoro-trichloro- ethane	Mixtures of trifluoro-trichloro-ethane with ethanol and isopropanol	Manufacturer
Freon TF	Freon TE 35; Freon TP 35; Freon TES	Du Pont
Frigen 113 TR	Frigen 113 TR-E; Frigen 113 TR-P; Frigen TR-E 35	Hoechst
Arklone P	Arklone A; Arklone L; Arklone K	ICI
Kaltron 113 MDR	Kaltron 113 MDA; Kaltron 113 MDI; Kaltron 113 MDI 35	Kali-Chemie
Flugene 113	Flugene 113 E; Flugene 113 IPA	Rhone-Progil

## Table B (worldwide banned substances)

Manufacturers' designations for unsuitable cleaning solvents (selection)

Mixtures of chlorinated hydrocarbons and ketones with fluorated hydrocarbons	Manufacturer
Freon TMC; Freon TA; Freon TC	Du Pont
Arklone E	ICI
Kaltron 113 MDD; Kaltron 113 MDK	Kali-Chemie
Flugene 113 CM	Rhone-Progil



## 3 Embedding of capacitors in finished assemblies

In many applications, finished circuit assemblies are embedded in plastic resins. In this case, both chemical and thermal influences of the embedding ("potting") and curing processes must be taken into account.

Our experience has shown that the following potting materials can be recommended: non-flexible epoxy resins with acid-anhydride hardeners; chemically inert, non-conducting fillers; maximum curing temperature of 100  $^{\circ}$ C.

## Caution:

Consult us first if you wish to embed uncoated types!





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## Cautions and warnings

- Do not exceed the upper category temperature (UCT).
- Do not apply any mechanical stress to the capacitor terminals.
- Avoid any compressive, tensile or flexural stress.
- Do not move the capacitor after it has been soldered to the PC board.
- Do not pick up the PC board by the soldered capacitor.
- Do not place the capacitor on a PC board whose PTH hole spacing differs from the specified lead spacing.
- Do not exceed the specified time or temperature limits during soldering.
- Avoid external energy inputs, such as fire or electricity.
- Avoid overload of the capacitors.

The table below summarizes the safety instructions that must always be observed. A detailed description can be found in the relevant sections of the chapters "General technical information" and "Mounting guidelines".

Торіс	Safety information	Reference chapter "General technical information"
Storage conditions	Make sure that capacitors are stored within the specified range of time, temperature and humidity conditions.	4.5 "Storage conditions"
Flammability	Avoid external energy, such as fire or electricity (passive flammability), avoid overload of the capacitors (active flammability) and consider the flammability of materials.	5.3 "Flammability"
Resistance to vibration	Do not exceed the tested ability to withstand vibration. The capacitors are tested to IEC 60068-2-6. EPCOS offers film capacitors specially designed for operation under more severe vibration regimes such as those found in automotive applications. Consult our catalog "Film Capacitors for Automotive Electronics".	5.2 "Resistance to vibration"



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Торіс	Safety information	Reference chapter "Mounting guidelines"
Soldering	Do not exceed the specified time or temperature limits during soldering.	1 "Soldering"
Cleaning	Use only suitable solvents for cleaning capacitors.	2 "Cleaning"
Embedding of capacitors in finished assemblies	When embedding finished circuit assemblies in plastic resins, chemical and thermal influences must be taken into account. Caution: Consult us first, if you also wish to embed other uncoated component types!	3 "Embedding of capacitors in finished assemblies"





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## Symbols and terms

Symbol	English	German
α	Heat transfer coefficient	Wärmeübergangszahl
$\alpha_{c}$	Temperature coefficient of capacitance	Temperaturkoeffizient der Kapazität
Α	Capacitor surface area	Kondensatoroberfläche
βc	Humidity coefficient of capacitance	Feuchtekoeffizient der Kapazität
С	Capacitance	Kapazität
C <sub>R</sub>	Rated capacitance	Nennkapazität
$\Delta C$	Absolute capacitance change	Absolute Kapazitätsänderung
$\Delta C/C$	Relative capacitance change (relative	Relative Kapazitätsänderung (relative
	deviation of actual value)	Abweichung vom Ist-Wert)
$\Delta C/C_R$	Capacitance tolerance (relative deviation	Kapazitätstoleranz (relative Abweichung
	from rated capacitance)	vom Nennwert)
dt	Time differential	Differentielle Zeit
$\Delta t$	Time interval	Zeitintervall
$\Delta T$	Absolute temperature change	Absolute Temperaturänderung
	(self-heating)	(Selbsterwärmung)
∆tan δ	Absolute change of dissipation factor	Absolute Änderung des Verlustfaktors
$\Delta V$	Absolute voltage change	Absolute Spannungsänderung
dV/dt	Time differential of voltage function (rate	Differentielle Spannungsänderung
	of voltage rise)	(Spannungsflankensteilheit)
$\Delta V / \Delta t$	Voltage change per time interval	Spannungsänderung pro Zeitintervall
E	Activation energy for diffusion	Aktivierungsenergie zur Diffusion
ESL	Self-inductance	Eigeninduktivität
ESR	Equivalent series resistance	Ersatz-Serienwiderstand
f	Frequency	Frequenz
f <sub>1</sub>	Frequency limit for reducing permissible	Grenzfrequenz für thermisch bedingte
	AC voltage due to thermal limits	Reduzierung der zulässigen
		Wechselspannung
f <sub>2</sub>	Frequency limit for reducing permissible	Grenzfrequenz für strombedingte
	AC voltage due to current limit	Reduzierung der zulässigen
,		Wechselspannung
f <sub>r</sub>	Resonant frequency	Resonanzfrequenz
F <sub>D</sub>	Thermal acceleration factor for diffusion	Therm. Beschleunigungsfaktor zur Diffusion
F⊤	Derating factor	Deratingfaktor
i	Current (peak)	Stromspitze
I <sub>c</sub>	Category current (max. continuous	Kategoriestrom (max. Dauerstrom)
	current)	· · · · · · · · · · · · · · · · · · ·



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Symbol	English	German
I <sub>RMS</sub>	(Sinusoidal) alternating current, root-mean-square value	(Sinusförmiger) Wechselstrom
i <sub>z</sub>	Capacitance drift	Inkonstanz der Kapazität
k <sub>o</sub>	Pulse characteristic	Impulskennwert
Ls	Series inductance	Serieninduktivität
λ	Failure rate	Ausfallrate
λο	Constant failure rate during useful	Konstante Ausfallrate in der
	service life	Nutzungsphase
$\lambda_{\text{test}}$	Failure rate, determined by tests	Experimentell ermittelte Ausfallrate
$P_{diss}$	Dissipated power	Abgegebene Verlustleistung
$P_{gen}$	Generated power	Erzeugte Verlustleistung
Q	Heat energy	Wärmeenergie
ρ	Density of water vapor in air	Dichte von Wasserdampf in Luft
R	Universal molar constant for gases	Allg. Molarkonstante für Gas
R	Ohmic resistance of discharge circuit	Ohmscher Widerstand des
		Entladekreises
Ri	Internal resistance	Innenwiderstand
R <sub>ins</sub>	Insulation resistance	Isolationswiderstand
R <sub>P</sub>	Parallel resistance	Parallelwiderstand
Rs	Series resistance	Serienwiderstand
S	severity (humidity test)	Schärfegrad (Feuchtetest)
t	Time	Zeit
Т	Temperature	Temperatur
τ	Time constant	Zeitkonstante
tan δ	Dissipation factor	Verlustfaktor
$tan \ \delta_{\scriptscriptstyle D}$	Dielectric component of dissipation factor	Dielektrischer Anteil des Verlustfaktors
$tan \delta_P$	Parallel component of dissipation factor	Parallelanteil des Verlfustfaktors
$tan \delta_s$	Series component of dissipation factor	Serienanteil des Verlustfaktors
T <sub>A</sub>	Ambient temperature	Umgebungstemperatur
T <sub>max</sub>	Upper category temperature	Obere Kategorietemperatur
T <sub>min</sub>	Lower category temperature	Untere Kategorietemperatur
t <sub>oL</sub>	Operating life at operating temperature	Betriebszeit bei Betriebstemperatur und
	and voltage	-spannung
T <sub>op</sub>	Operating temperature	Beriebstemperatur
T <sub>R</sub>	Rated temperature	Nenntemperatur
$T_{ref}$	Reference temperature	Referenztemperatur
t <sub>SL</sub>	Reference service life	Referenz-Lebensdauer
V <sub>AC</sub>	AC voltage	Wechselspannung





General purpose (wound)

Symbol	English	German
Vc	Category voltage	Kategoriespannung
$V_{C,RMS}$	Category AC voltage	(Sinusförmige)
		Kategorie-Wechselspannung
V <sub>CD</sub>	Corona-discharge onset voltage	Teilentlade-Einsatzspannung
$V_{ch}$	Charging voltage	Ladespannung
V <sub>DC</sub>	DC voltage	Gleichspannung
$V_{\text{FB}}$	Fly-back capacitor voltage	Spannung (Flyback)
Vi	Input voltage	Eingangsspannung
Vo	Output voltage	Ausgangssspannung
V <sub>op</sub>	Operating voltage	Betriebsspannung
V <sub>p</sub>	Peak pulse voltage	Impuls-Spitzenspannung
$V_{pp}$	Peak-to-peak voltage Impedance	Spannungshub
V <sub>R</sub>	Rated voltage	Nennspannung
ν <sub>R</sub>	Amplitude of rated AC voltage	Amplitude der Nenn-Wechselspannung
V <sub>RMS</sub>	(Sinusoidal) alternating voltage,	(Sinusförmige) Wechselspannung
	root-mean-square value	
V <sub>sc</sub>	S-correction voltage	Spannung bei Anwendung "S-correction"
$V_{sn}$	Snubber capacitor voltage	Spannung bei Anwendung
		"Beschaltung"
Z	Impedance	Scheinwiderstand
е	Lead spacing	Rastermaß

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